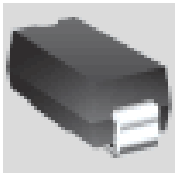


MATERIAL DECLARATION SHEET

Material #	CD214C-TxxxLF Series	
Product Line	Integrated Passive & Active Devices	
Date	8/2/2004	
RoHS Compliant	Yes	

COMPONENT DETAILS

No.	Construction element	Material group	Material weight [g]	Materials	CAS if applicable	Average mass [%]	Sum [%]	Traces
1	Dice	Silicon with metal	0.0105	Si	7440-21-3	4.9	5	Al, B, P, Pt, Cu,
				Ni	7440-02-0	.055		
2	High-melting point Solder paste	Tin-Lead solder	0.0042	Pb	7439-92-1	1.87	2	
				Sn	7440-31-5	.1		
				Ag	7440-22-4	.03		
3	Lead frame & clip	Copper alloy	0.0882	Cu	7440-50-8	41.05	42	Zn,P
				Fe	7439-89-6	.8946		
4	Mold compound	Epoxy material	0.1050	Silica(SiO2)	7631-86-9	35	50	
				Epoxy resin	68928-70-1	10		
				Sb2O3	1309-64-4	2.5		
				Phenolic resin	29690-82-2	2.5		
5	Plating cover	Tin Solder	0.0021	Sn	7440-31-5	1	1	
		Total weight	0.2100					

Note: Avg. mass and sum data is a % of the component weight.
It is the responsibility of the user to ensure that the latest revision is being accessed on the website.